## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: J.-S. Mok et al. Attorney Docket No.: LEPA121687

Application No.: 10/677,182 Art Unit: 1765 / Confirmation No: 8329

Filed: October 3, 2003 Examiner: S. Ahmed

Title: METHOD OF FORMING SOLDER RESIST PATTERN

## AMENDMENT SUBMITTED WITH RCE

Seattle, Washington 98101

October 30, 2007

## TO THE COMMISSIONER FOR PATENTS:

## INTRODUCTORY COMMENTS

In response to the Office Action of September 12, 2007, please amend the above-identified patent application as follows:

Amendments to the Claims are reflected in the listing of the claims, which begins on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.